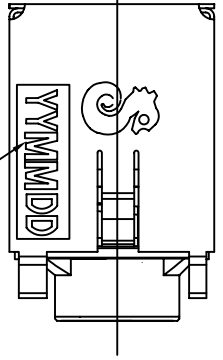
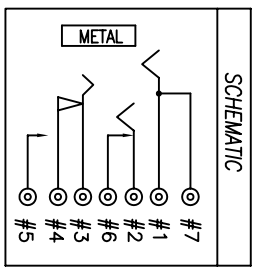
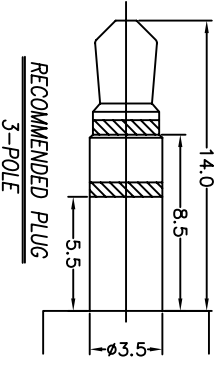


RECOMMENDED PCB LAYOUT (TOP VIEW)
(TOLERANCE: ±0.05)



- SPECIFICATIONS:
- INSULATION RESISTANCE BETWEEN ANY ADJACENT OPEN CIRCUIT TERMINAL SHELL NOT BE LESS THAN 100MΩ MEASURED BY 500 VDC MEGGER.
 - CONTACT RESISTANCE: 30mΩ MAX. (200mΩ MAX: METAL TO EARTH TO SHIELDING)
 - INSULATION VOLTAGE WITHSTAND: 500V AC FOR ONE MINUTE.
 - UNLESS OTHERWISE SPECIFIED, TEST IS TO BE MADE AT 5-35°C IN TEMPERATURE AND 45-85% IN HUMIDITY. BUT, IF ANY VAGUE DATA IS OCCURED ON TEST RESULT, ANOTHER TEST SHALL BE MADE AT 20°C±2°C IN TEMP., 60-70% IN HUMIDITY.
 - LIFE TEST: 5,000 CYCLES MIN. (NON-LOAD)
 - INSERTION FORCE: 0.4 - 3Kg.
 - WITHDRAWAL FORCE: 0.3 - 2Kg.
 - AFTER LIFE TEST, CONTACT RESISTANCE: 50mΩ MAX.
 - AFTER HUMIDITY TEST, INSULATION RESISTANCE: 50MΩ MIN.
 - MARKING: MARK "S" ON TOP OF CONNECTOR.
 - PACKING: TAPE & REEL.
 - TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
 - HALOGEN FREE PRODUCT IDENTIFICATION MARK ON PRODUCT:
 - HALOGEN FREE PRODUCT IDENTIFICATION LOGO ON PACKING:
 - FOR LEAD-FREE PROCESS.

NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
I	METAL	1	BRASS	Ni 1.5 μm MIN.
H	SHIELDING	1	PHOSPHOR BRONZE 0.2t	Ni 1.5 μm MIN.
G	TRANSFER TERMINAL	1	PHOSPHOR BRONZE 0.2t	Ag0.5 μm Min Over 1.5 μm Min Ni
F	BREAK TERMINAL	1	PHOSPHOR BRONZE 0.2t	Ag0.5 μm Min Over 1.5 μm Min Ni
E	SHUNT TERMINAL-A	1	BRASS 0.25t	Ag0.5 μm Min Over 1.5 μm Min Ni
D	RING SPRING	1	PHOSPHOR BRONZE 0.2t	Ag0.5 μm Min Over 1.5 μm Min Ni
C	TIP SPRING	1	PHOSPHOR BRONZE 0.25t	Ag0.5 μm Min Over 1.5 μm Min Ni
B	EARTH	1	COPPER ALLOY 0.2t	Ag0.5 μm Min Over 1.5 μm Min Ni
A	BODY	1	HIGH TEMP.THERMOPLASTIC UL 94V-0	BLACK

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS: ANGLES:

±0.5 X ±2
±0.3 X.X ±1°
X.XX ±0.2
X.XXX ±0.1

DATE CODE: YYMMDD

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REV	ECN NO OR DESCRIPTION	REVISED	DATE
A	PDR NO. T080807-34	GIND	2008.09.05
B	ECN NO:T080402	LILI	2008.12.29